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=======      WPI      =======
TI   - Waste sulphuric acid purificn. appts. - has distn. tower with
        degasification tower and toxic gas removal tower, used in cleaning
        process or etching process of wafers in semiconductor plants.
AB   - J08175810 In the waste sulphuric acid purificn. appts. comprising:
     - (a) a distn. tower (2) to store waste sulphuric acid; (b) heating means
        (3) to heat waste sulphuric stirred in the distn. tower and condenser (4)
        to cool and condense vapour of each component discharged from the distn.
        tower; (c) the distn. tower is equipped with a degasification tower (46)
        to store waste sulphuric acid contg. hydrogen peroxide and heat the
        waste sulphuric acid to decompose the hydrogen peroxide; and (d) toxic
        gas removal tower (48) to decompose ozone generated by decomposition of
        the hydrogen peroxide.
     - USE - Used to purify waste sulphuric acid used in a cleaning processor
        etching process of wafers in semiconductor plants or a peeling process
        of photoresists.
     - ADVANTAGE - Toxic gas does not exhaust and a time necessary for
        purifying sulphuric acid is significantly decreased.
     - (Dwg.1/5)
PN   - JP8175810 A 960709 DW9637 C01B17/90  008pp
PR   - JP940321016 941222
PA   - (NIIO ) NIPPON SANSO CORP
MC   - E11-Q01 E11-Q02 E11-T E31-F03 G06-D06 G06-E G06-G J01-A02A L04-C09
     - U11-A10 U11-C06A1B U11-C07B
DC   - E36 G06 J01 L03 U11
IC   - B01D3/00 ;C01B17/90
AN   - 96-367949 [37]
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=======      WPI      =======
TI   - Purificn. of sulphuric acid - by heating sulphuric acid contg. hydrogen
        peroxide in presence of sulphur@
AB   - J08073206 Purificn. comprises heating sulphuric acid contg. hydrogen
        peroxide in the presence of sulphur to decompose and remove the hydrogen
        peroxide contained in sulphuric acid.
     - The heating temp. is pref. 100-190 deg.C. The amt. of sulphur is pref.
        at least 0.01 wt. part for every 100 wt. parts of hydrogen peroxide in
        sulphuric acid.
     - USE/ADVANTAGE - The method is esp. useful when recovering sulphuric acid
        from waste sulphuric acid contg. hydrogen peroxide which has been used
        to remove photoresist in the semiconductor prodn. process. Hydrogen
        peroxide is removed easily and economically.
     - In an example, to 203 g of 80% sulphuric acid, 27.9 g of 35.2% hydrogen
        peroxide soln. was added, and the mixt. was stirred and heated over an
        oil bath, to which 1 g of sulphur was added. 99.6% of hydrogen peroxide
        was removed.(Dwg.0/0)
PN   - JP8073206 A 960319 DW9621 C01B17/90  003pp
PR   - JP940232455 940902
PA   - (NIRS ) NISSO ENG KK
MC   - E11-Q01 E31-E E31-F04 E31-F05
DC   - E36
IC   - C01B17/90
AN   - 96-205311 [34]
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